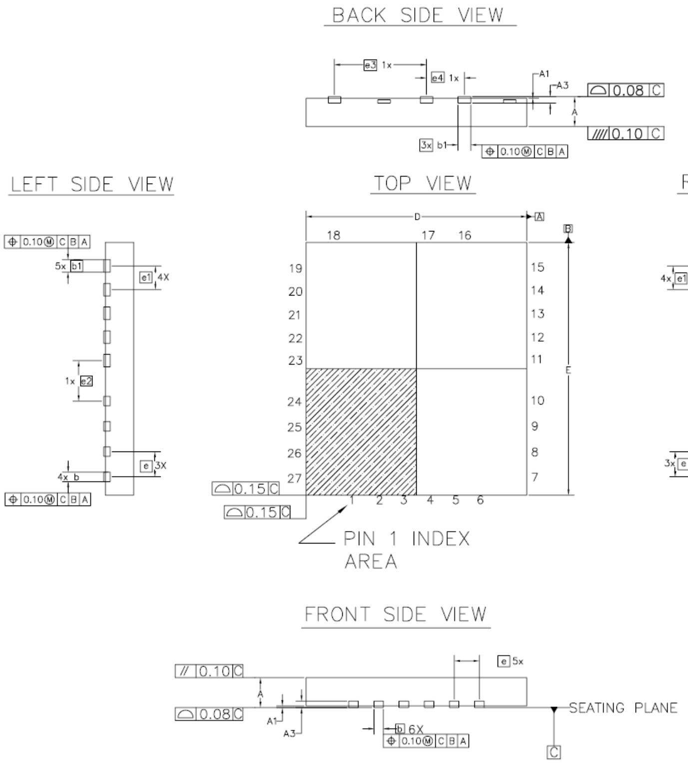
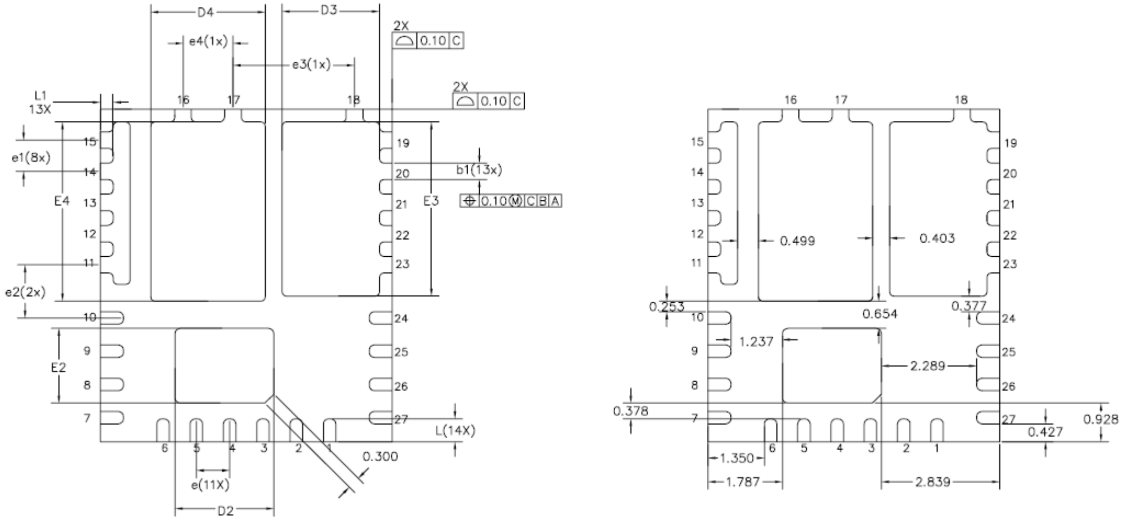
Package Outline (Top & Side view)



SYMBOL	DIMENSIONS IN MILLIMETER		
	MIN.	NOM.	MAX.
A	0.800	0.900	1.000
A1	0.000	–	0.050
A3	0.203 REF.		
b	0.250	0.300	0.350
b1	0.350	0.400	0.450
D	6.900	7.000	7.100
E	7.900	8.000	8.100
D2	2.323	2.373	2.423
E2	1.748	1.798	1.848
D3	2.290	2.340	2.390
E3	4.144	4.194	4.244
D4	2.698	2.748	2.798
E4	4.267	4.317	4.367
e	0.800 BSC		
e1	0.750 BSC		
e2	1.281 BSC		
e3	2.918 BSC		
e4	1.200 BSC		
L	0.500	0.550	0.600
L1	0.253	0.303	0.353

Package Outline (Bottom View, 1 of 2)

PACKAGE BOTTOM VIEW



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1. For mounting instruction see AN-1168.
2. For recommended PCB via design see AN-1091.
3. For recommended design, solder profile, integration and rework guidelines see AN-1028.
4. For board inspection guidelines see AN-1133.